

DECLARATION FOR NON-PROVISIONAL PATENT APPLICATION

As a below named inventor, I hereby declare that:

My residence, post office address and citizenship are as stated below at 201 et seq. beneath my name.

I believe I am the original, first and sole inventor if only one name is listed at 201 below, or an original, first and joint inventor if plural names are listed at 201 et seq. below, of the subject matter which is claimed and for which a patent is sought on the invention entitled

Polypropylene-based resin composition for powder slush molding

and which patent application bears attorney docket no. 11036-042-999

I hereby state that I have reviewed and understand the contents of the above identified application, including the claims.

I acknowledge the duty to disclose information known to me to be material to patentability as defined in Title 37, Code of Federal Regulations, '1.56.

I hereby claim foreign priority benefits under Title 35, United States Code, '119(a)-(d) of any foreign application(s) for patent or inventor's certificate listed below and have also identified below any foreign application for patent or inventor's certificate having a filing date before that of the application on which priority is claimed:

EARLIEST FOREIGN APPLICATION(S), IF ANY, FILED PRIOR TO THE FILING DATE OF THE APPLICATION			
APPLICATION NUMBER	COUNTRY	DATE OF FILING (day, month, year)	PRIORITY CLAIMED
2003-19263	Korea	27/03/03	YES <input checked="" type="checkbox"/> NO <input type="checkbox"/>
			YES <input type="checkbox"/> NO <input type="checkbox"/>
			YES <input type="checkbox"/> NO <input type="checkbox"/>

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issuing thereon.

2 0 1	FULL NAME OF INVENTOR	LAST NAME JEONG	FIRST NAME KIE YOUN	MIDDLE NAME	
	RESIDENCE & CITIZENSHIP	CITY Suwon-si, Gyeonggi-do	STATE OR FOREIGN COUNTRY REPUBLIC OF KOREA	COUNTRY OF CITIZENSHIP REPUBLIC OF KOREA	
	POST OFFICE ADDRESS	STREET Chongsolmaul Joogong Apt. 611-201, Jeongja-dong, Jangan-gu	CITY Suwon-si, Gyeonggi-do	STATE OR COUNTRY Republic of Korea	ZIP
SIGNATURE OF INVENTOR 201			DATE		
Jeong Kie Youn			28 July 2003		

2 0 2	FULL NAME OF INVENTOR	LAST NAME LEE	FIRST NAME SEUNG-WOOK	MIDDLE NAME	
	RESIDENCE & CITIZENSHIP	CITY Daejeon	STATE OR FOREIGN COUNTRY REPUBLIC OF KOREA	COUNTRY OF CITIZENSHIP REPUBLIC OF KOREA	
	POST OFFICE ADDRESS	STREET Daerimdure Apt. 109-1206, Sinseong-dong, Yuseong-gu	CITY Daejeon	STATE OR COUNTRY Republic of Korea	ZIP
	SIGNATURE OF INVENTOR 202 <i>Seung Wook, Lee</i>			DATE 28 July 2003	